

Silicon Carbide

From materials to devices,
modules & circuits

Patent Landscape Analysis

May 2022

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INTRODUCTION

Context of the report

THE SiC MARKET IS BOOMING, DRIVEN BY THE ADOPTION OF SILICON CARBIDE (SiC) POWER DEVICES IN ELECTRIC VEHICLES (EV)

In recent years, more and more automotive players have investigated the use of SiC power devices, especially in the EV main inverter controlling the motor. In 2018, with the release of the Model 3, **Tesla** was the first company to adopt power SiC technology in its in-house EV inverter, just before historical automakers such as **Hyundai**, **General Motors** and **BYD** also announced their intention to adopt power SiC in EV systems. **Tesla's** SiC power device supplier is **STMicroelectronics (ST)**, which holds a 40% share of the SiC power device market as of 2021. In Europe, the main competitor to **STMicroelectronics** is **Infineon**, the second-placed SiC power device manufacturer in terms of revenue in 2021, which exhibited a +126% rise in revenue in 2020/2021 by entering the main inverter business with the base of industrial applications [1]. What's more, **Infineon** will supply **Hyundai** with SiC power modules for the production of its 800-V battery platforms. The competition will also come from **Danfoss** and **Semikron**, which joined forces in the power module business in 2022, and are currently the main European challengers in the SiC power device market. In North America, the main market player is **Wolfspeed**, which is also the world leading supplier of SiC wafers, and has multiple long-term supply agreements (LTSA) with several top-6 power device makers (**ST**, **Infineon**). **Wolfspeed** also signed an LTSA with **onsemi**, which is the main challenger in North America (far ahead of **GeneSiC**, **UnitedSiC** and **Microchip** in terms of revenue) and exhibited rapid growth in 2020/2021, similar to that of other leading power device makers (**ST**, **Wolfspeed**). Finally, in Asia, the competition mainly comes from **Rohm Semiconductor** in Japan, which has doubled its revenue since 2017 and ranked fourth in the SiC power device market in 2021. Furthermore, major Japanese corporations are preparing for power SiC ramp-up as well, and have already demonstrated significant market revenue, including **Mitsubishi Electric**, **Fuji Electric** and **Toshiba**.

THE SiC INDUSTRY IS ADAPTING TO LIMIT THE RISKS RELATED TO WAFER SUPPLY AND COST COMPETITIVENESS

Growing SiC crystals is a long and difficult process, and making high-quality and large-area SiC wafers is still expensive, so the number of companies capable of supplying such wafers is very limited. In order to alleviate both problems, major SiC power device players have signed LTSAs with multiple SiC wafer suppliers (e.g., **Infineon** with **Wolfspeed** and **Showa Denko**, **ST** with **Wolfspeed** and **SiCrystal**), and/or adopted a vertical integration model by acquiring SiC material suppliers for substrate self-supply (e.g., **ST** acquired **Norstel**, **Rohm** acquired **SiCrystal**, **onsemi** acquired **GTAT**), reshaping the SiC ecosystem [2]. Furthermore, more and more SiC wafer suppliers are developing the technology for 200mm SiC wafers, which are expected to be cheaper eventually than their 150mm counterparts and thereby represent a mid-term or long-term solution [2]. Several manufacturers are sampling 200mm SiC wafers (**Wolfspeed**, **II-VI**, **SiCrystal**, **ST**, **GTAT**, **SK Siltron CSS**). In the meantime, several companies are developing disruptive technologies to address the cost and supply issues and have now entered the SiC ecosystem (e.g., **Sillectra**, **Disco** providing laser slicing/thinning; and more recently **Soitec** and **Sumitomo Metal Mining** providing SiC engineered substrates).

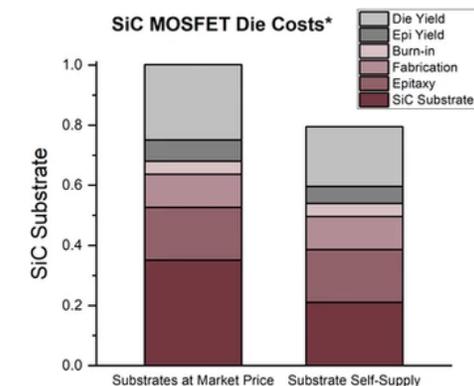
CHINA AIMS TO BUILD A DOMESTIC SUPPLY CHAIN FOR POWER SiC TECHNOLOGY

It seems that China has been a little bit late to develop its SiC industry, but is now willing to catch up at all levels of the value chain, funding numerous SiC industrial and R&D projects in recent years. As an example of Chinese ambitions to serve its own market, in 2021, **San'an Optoelectronics**, a new entrant in the power SiC landscape, announced the establishment of China's first vertically-integrated SiC line, representing a \$2.5B investment. However, for a new player in SiC to meet the material quality required by SiC power devices would normally not only require strong expertise and big investment, but also many years of development in crystal & epitaxial growth, slicing, polishing, etc., not to mention the difficulty of SiC device manufacturing and testing, and tough requirements from automotive applications (the main market for power SiC). Accordingly, the current development of power SiC technology in China raises many questions in the SiC industry.

SAMPLE

Rank	Area	Company	2020	2021
1	Europe	STMicroelectronics	\$290M	\$450M
2	Europe	Infineon Technologies	\$110M	\$248M
3	North America	Wolfspeed	\$108M	\$165M
4	Asia	ROHM	\$103M	\$108M
5	North America	onsemi	\$55M	\$78M
6	Asia	Mitsubishi Electric	\$26M	\$28M

2020-2021 revenue – Top 6 SiC power device makers [1]



*Based on PGC's 1200V/100A die cost model

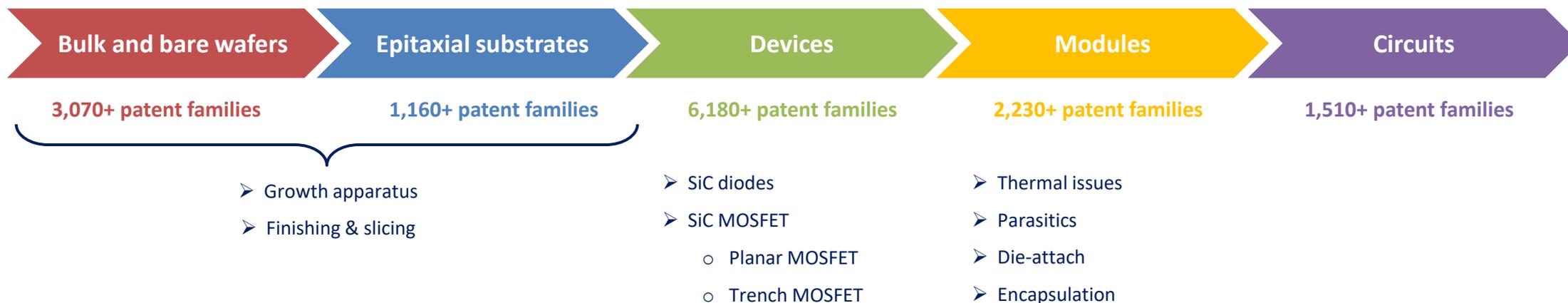
The cost breakdown of a SiC MOSFET die, based on a best-in-class 2021 1200V/100A device on a 150mm substrate [2]

INTRODUCTION

Description of the report

SAMPLE

The report aims to provide a comprehensive view of the **power SiC patent landscape** along the whole supply chain / value chain, which has been split in the following 5 main categories and 10 main sub-categories:



More in details, the patent landscape analysis provides an overview of **power SiC patent landscape**:

- To describe **global patenting trends** (time evolution of patent filings, geographical evolution of patent filings);
- To identify the **main IP players** and the **newcomers** in the different segments of the supply chain;
- To determine the status of their **patenting activity** (active / inactive) and their **dynamics** (ramping up, slowing down, steady);
- To identify the **IP collaborations** (patent co-filings) and **IP transfers** (changes of patent ownership) in the power SiC patent landscape;
- To provide a detailed picture of the **Chinese SiC ecosystem** focusing on the patenting activity of Chinese entities.

In addition, the patent landscape analysis includes **IP profiles**, which provide an overview of the patent portfolios and the recent patenting activity of the **top 10 IP players** and **top 6 power device market players**.

INTRODUCTION

Scope of the report

- This report provides a detailed picture of the patent landscape related to **Silicon Carbide (SiC)**:
 - **Bulk SiC** (growth methods, growth apparatus)
 - **Epitaxial SiC wafers** (homo-epitaxial growth methods, growth apparatus for SiC epitaxy)
 - **SiC devices** (MOSFET, JFET, MESFET, bipolar devices)
 - **SiC modules and circuits**
- This report covers patents published worldwide up to **August 2021**.
- We have selected and analyzed more than **13,700 patent families** (inventions) relevant to the scope of this report.



Included

- SiC substrate patents describing growth apparatus for **crystal growth (bulk)** and **epitaxial growth (thin films)**.
- SiC substrate patents related to **wafering (slicing, finishing)**.
- SiC substrate patents describing **SiC-on-SiC epitaxial structures**.
- SiC device patents describing **electronic devices** (MOSFET, IGBT, JFET, diodes, etc.).
- Power module patents describing **based on WBG devices**.
- WBG circuit patents describing **circuits and operating methods specific to SiC devices**.
- WBG circuit patents describing **driver and protection circuits for Wide bandgap (WBG) devices**.

Excluded

- SiC substrate patents claiming materials different from SiC (generic patents)
- SiC substrate patents describing **heterostructures (SiC-on-X, X is not SiC)**
- SiC device patents describing **other devices (optoelectronic devices, sensors, MEMS, etc.)**
- WBG power module patents including specifically **GaN devices**.
- WBG circuit patent describing **circuits and operating methods not specific to SiC devices**.
- WBG circuit patent describing **driver and protection circuits for GaN specifically**.

Patent landscape overview

General trends, key patent assignees and newcomers along the SiC supply chain

SAMPLE

Focus on Chinese ecosystem

EXECUTIVE SUMMARY
Patent landscape overview: a consolidation of the SiC ecosystem

EXECUTIVE SUMMARY
Timeline of SiC patent publications vs. Supply chain

EXECUTIVE SUMMARY
IP newcomers in the power SiC patent landscape (since 2015)

EXECUTIVE SUMMARY
IP Profiles

EXECUTIVE SUMMARY
SiC substrates: new technologies to enhance SiC wafer supply and cost

EXECUTIVE SUMMARY
Main IP players along the power SiC supply chain (Top 20 IP players)

EXECUTIVE SUMMARY
Main IP players along the power SiC supply chain

EXECUTIVE SUMMARY
Focus on China: jumping over the high entry barrier in the SiC material business

EXECUTIVE SUMMARY
Focus on China: Ranking of the main IP players

EXECUTIVE SUMMARY
Focus on China: Chinese IP players with international ambitions (filing patents abroad)

EXECUTIVE SUMMARY
Focus on China: Timeline of patent and scientific publications

EXECUTIVE SUMMARY
Focus on China: Main Chinese IP players along the power SiC supply chain

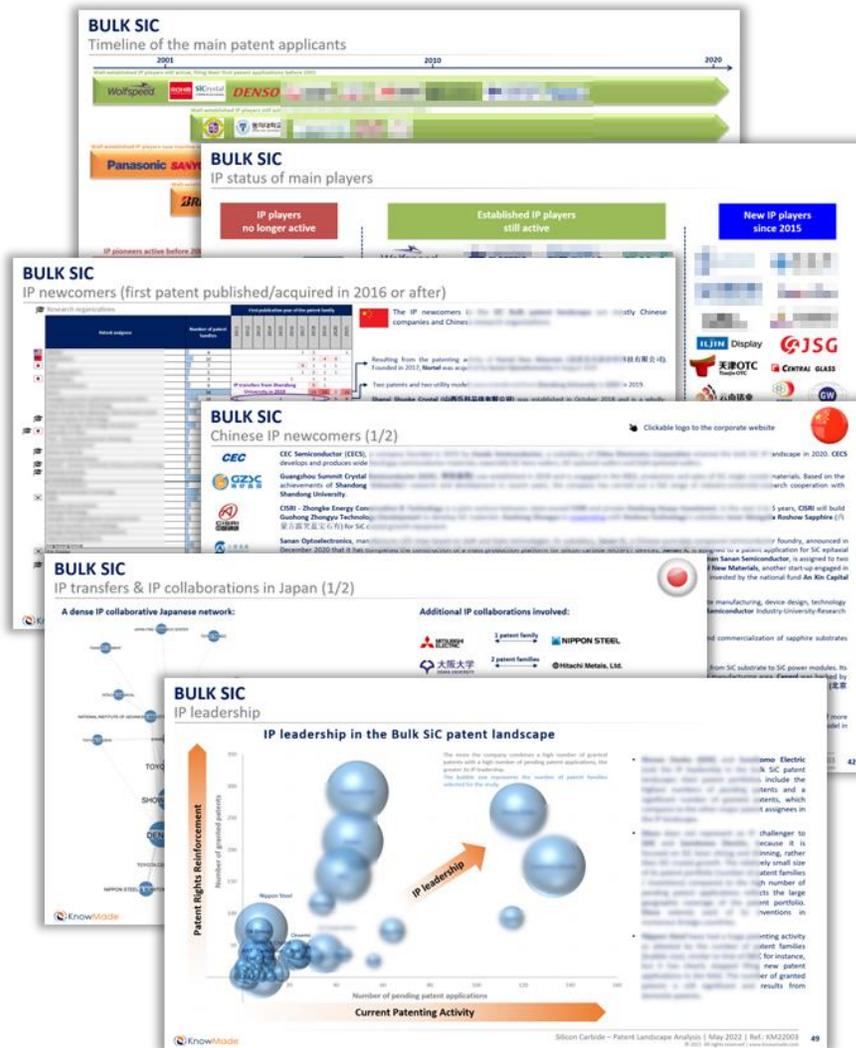
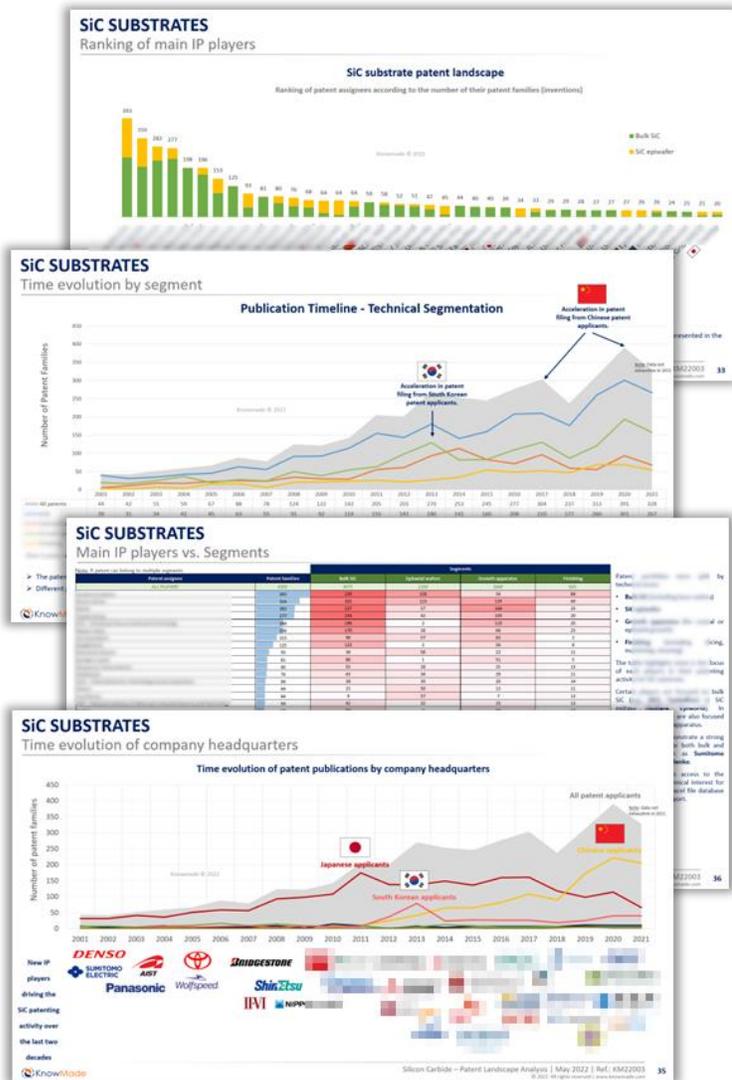
SiC substrates

General trends, Key patent assignees, Newcomers, IP collaborations, Patent legal status

SAMPLE

Focus on bulk SiC

Focus on epitaxial SiC substrates



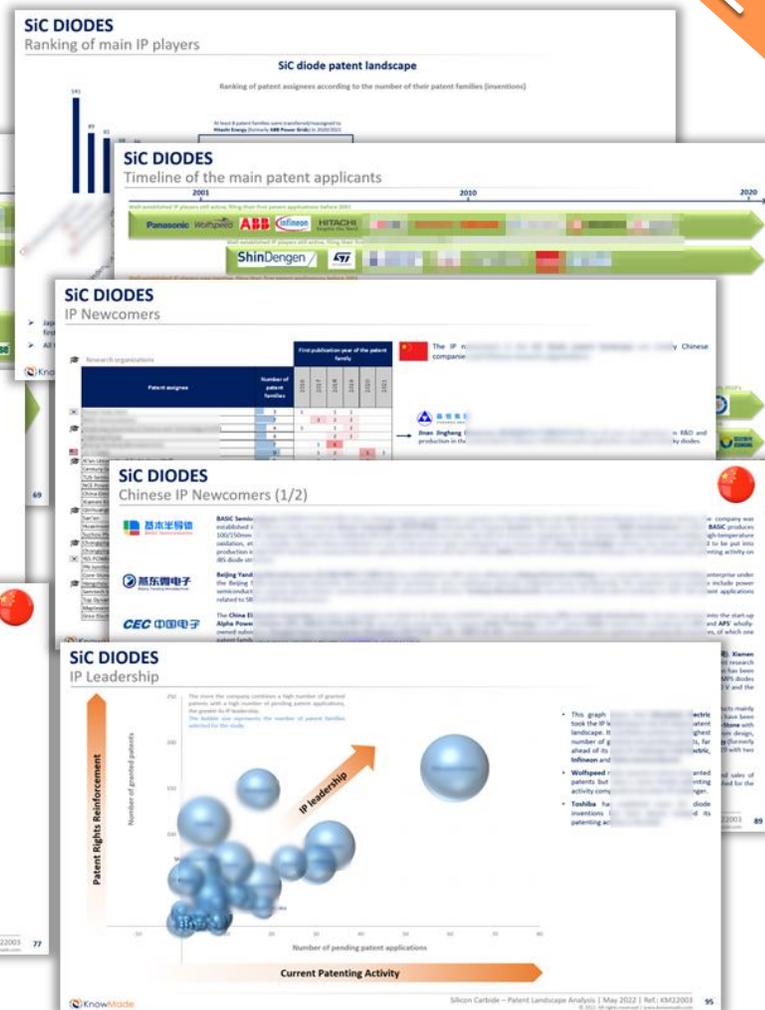
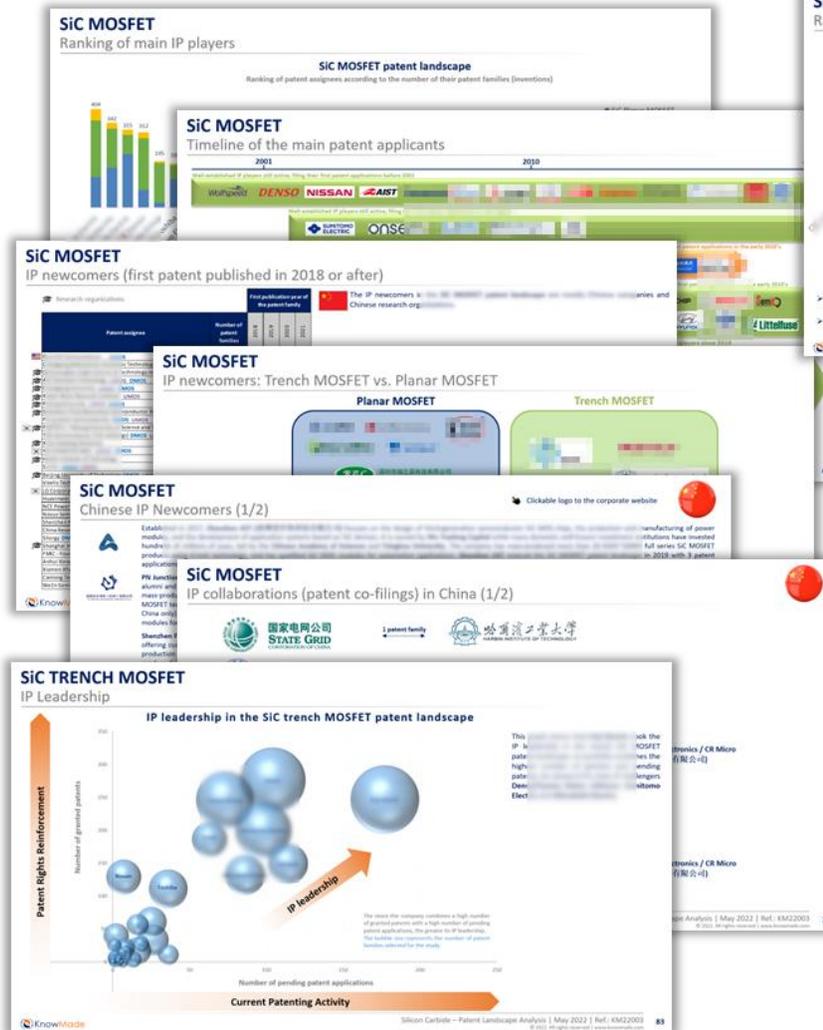
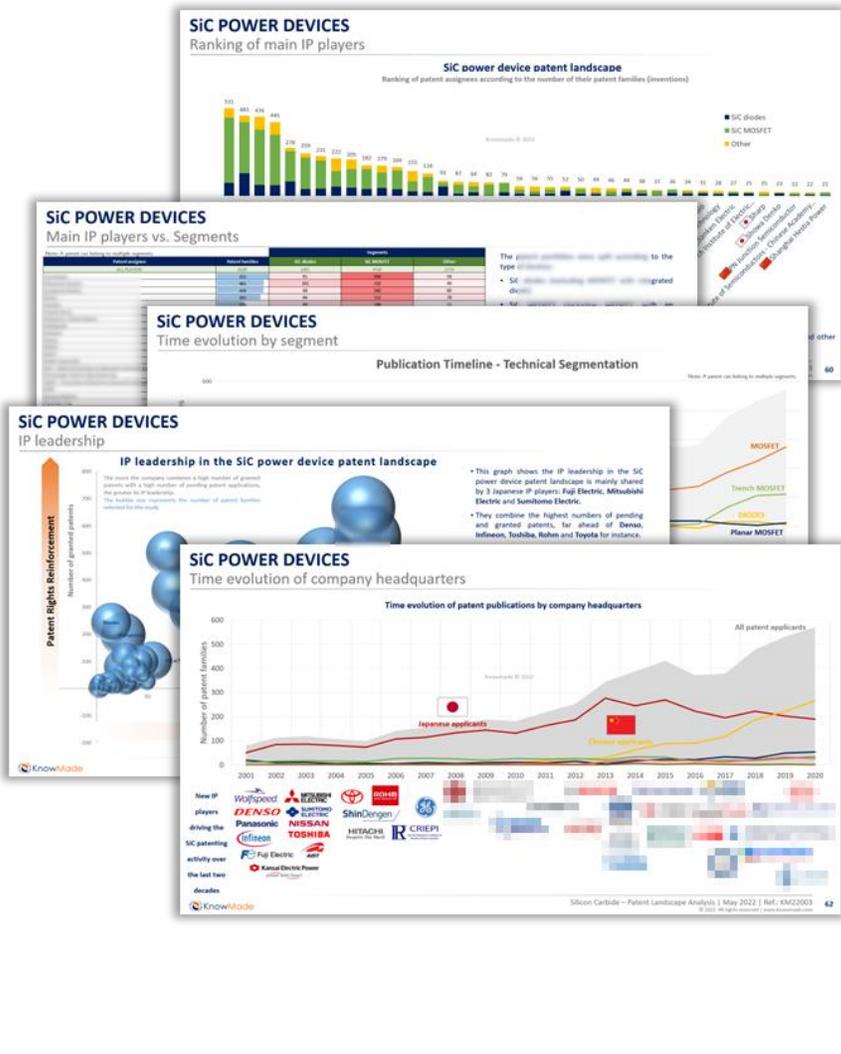
SiC power devices

General trends, Key patent assignees, Newcomers, IP collaborations, Patent legal status

SAMPLE

Focus on SiC planar MOSFETs and trench MOSFETs

Focus on SiC diodes



SiC circuits

General trends, Key patent assignees, Newcomers, IP collaborations, Patent legal status

SAMPLE

SiC CIRCUITS
Ranking of main IP players

SiC CIRCUITS
Timeline of the main patent applicants

SiC CIRCUITS
Ranking of patent assignees according to the number of their patent families (inventions)

SiC CIRCUITS
IP Leadership

SiC CIRCUITS
IP status of main players

SiC CIRCUITS
Time evolution of company headquarters

SiC CIRCUITS
Time evolution of patent publications by company headquarters

SiC CIRCUITS
IP collaborations (patent co-filings)

SiC CIRCUITS
Non-Chinese IP Newcomers

IP profile of key players

IP portfolio summary, IP strategy, key patents and recent IP activity

SAMPLE

A focus on the top 10 IP players and top 6 power device market players is provided in a dedicated section. For each player, the SiC patent portfolio is statistically analyzed to provide an overview of its strengths, its potential for reinforcement and level of IP activity. The recent patenting activity of the player is then reviewed in light of recent announcements related to SiC and related challenges.



MITSUBISHI ELECTRIC Patent portfolio overview

MITSUBISHI ELECTRIC Trench MOSFET technology: Latest developments (1/3)

Infineon SiC MOSFET

STMicroelectronics Development of power SiC technology and patenting activity

ROHM / SiC CRYSTAL Power modules

WOLFSPEED SiC MOSFET

ORDER FORM

Silicon Carbide (SiC)

Patent Landscape Analysis – May 2022

Ref.:KM22003



SHIP TO

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Job Title:

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State:

Postcode/Zip:

Country:

VAT ID Number for EU members:

Tel:

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06902 Sophia Antipolis
FRANCE

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IBAN: FR76 1460 7003 6360 6214 5695 139
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BIC or SWIFT code: CCBPFRPPMAR

IBAN: : FR76 1460 7003 6360 6214 5695 139

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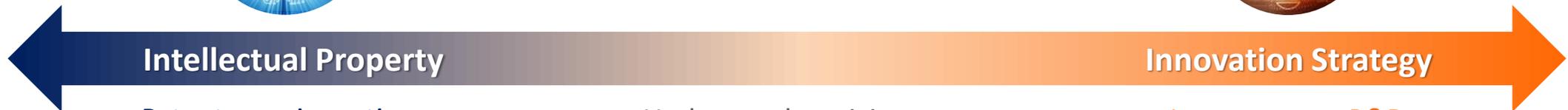
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Competitive landscape | Technology trends | Opportunities / Risks | R&D and IP strategy



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Patent your inventions
Assert your patents and defend your position in case of licensing/litigation
Evaluate the risks to infringe patents

Prior art search, Freedom-to-operate analysis, Patent invalidation, Evidence of use, Patent valuation

Understand, anticipate and evaluate the competitive landscape and current technology developments

Patent landscape, Monitoring service, IP due diligence

Innovation Strategy

Improve your R&D and IP strategy
Identify and get access to external innovation

Technology scouting, Scientific literature analysis

MAIN FIELDS OF EXPERTISE

Wireless and Optical Communications

- RF components & modules
- Antenna & Networks
- Photonics (datacom/telecom)



Advanced Packaging
Innovative Materials
AI & Computing

Energy Mgt & Storage

- Power electronics
- Batteries & Fuel-cells
- PV



Sensors and Optoelectronics

- MEMS
- Sensors & Imaging
- Lighting & Display

Life Sciences and Healthcare

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